



晶 湛 半 导 体 Enkris Semiconductor, Inc.

Professional GaN Material Manufacturer 专业氮化镓材料制造商



Professional GaN Material Manufacturer

Company Overview

We are dedicated to providing high quality GaN epiwafers for Power electronic, RF and Micro-LED applications.

History

 Founded in 2012 as a pure epi-foundry of GaN wafers

Technology

- Patented technology covering substrate engineering, buffer design, active region optimization for high quality, flat and crack free epi-structures.
- Core technical team members all have 10+ years experience in GaN

Capacity

- 3300m² class 1000 cleanroom
- 200k pcs/year for 150mm GaN epiwafers

Product Diversity

- GaN-on-Si (up to 300mm)
- GaN-on-SiC (up to 150mm)
- GaN-on-HR Si (up to 200mm)
- GaN-on-Sapphire (up to 150mm)
- GaN-on-GaN

IP & Quality

- ~400 patent filed in China, US, Japan etc. with >100 granted
- License of ~80 patents from imec
- ISO9001:2015 certificate for design and manufacture of GaN epi materials

Optimised stress management technology

Enabling flat and crack-free GaN epiwafers on large-size
 Si

Customized design

 Achieving high performance to meet customers' requirements

Unique passivation technology

· Avoiding current collapse at high voltage

Specific processing flow

Developing for particular structural and device design



Enkris GaN Epiwafers

Power

GaN-on-Si (100mm,150mm,200mm,300mm) D-mode and E-mode Breakdown Voltage available from 200V to 1200V

RI

GaN-on-HR_Si (100mm,150mm,200mm) GaN-on-SiC (50.8mm,100mm,150mm) In-situ SiN/ Al(In)N/ GaN heterostructures

LEC

GaN-on-Sapphire (50.8mm,100mm,150mm) GaN-on-Si (100mm,150mm,200mm,300mm) UVC, Near-UV, Blue, Green & Red



100mm GaN-on-SiC Epi Wafer (up to 150mm)



100mm GaN-on-Sapphire Epi Wafer (up to 150mm)



150mm GaN-on-HR_Si Epi Wafer (up to 200mm)



200mm GaN-on-Si Epi Wafer (up to 300mm)

For Power Application

Product Specification

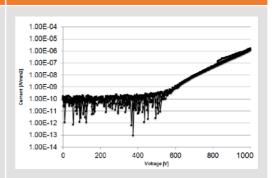
Items	Values/Scope
Substrate	Si
Wafer diameter	100mm,150mm,200mm,300mm
Epi-layer thickness	2-7 μm
Wafer bow	<30 μm, Typical
Surface Morphology	RMS<0.5nm in $5\times5~\mu\text{m}^2$
Barrier	Al _x Ga _{1-x} N, 0 <x<1< td=""></x<1<>
Cap layer	In-situ SiN or GaN (D-mode); p-GaN (E-mode)
2DEG density	>9E12/cm² (20nm Al _{0.25} GaN, 150mm)
Electron mobility	>1800 cm ² /Vs (20nm Al _{0.25} GaN, 150mm)

200mm GaN-on-Si Epiwafer

Defect Mapping

Defects Counts Crack 45 Epi 0 Micropits 4 Particle 40

Vertical Breakdown Behavior

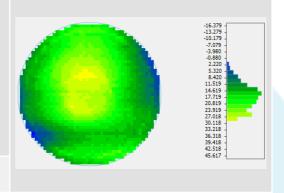


Sheet Resistance Mapping



Avg.= 309.12 Ω/ Std.= 1.2%

Wafer Bow Mapping



Highlights of GaN HEMT on Si

pGaN/GaN/SiNx cap

AlGaN barrier

GaN channel

(AI)GaN buffer

AIN NL

Si substrate

Optimising AIN nucleation layer

Enable crack-free thick AlGaN or GaN buffer layer

Stress engineering

Introduction of compliant substrates Interlayer technology

Buffer layer

High vertical breakdown voltage (for lateral devices)
Minimise wafer bow

Good defect control

Cracks Micropits

Particles

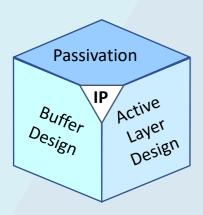
GaN layer for D-MODE

pGaN layer for E-MODE

In-situ SiNx passivation layer

IP & Quality

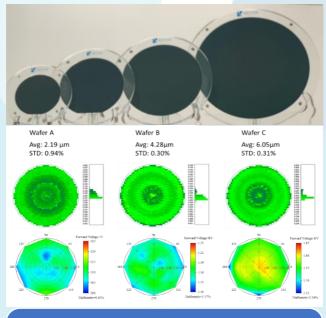
- ~400 patent filed in China, US, Japan etc. with >100 granted
- ISO9001:2015 design and manufacture of GaN epi materials
- Multiple inspection methods: PL, XRD, EL, Defect Inspection, etc.







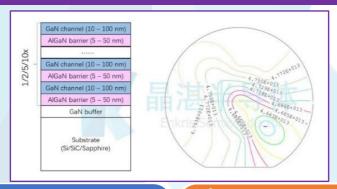
Recent Progress with 300mm GaN-on-Si HEMT



Highlights:

- Based on totally Enkris owned IP;
- A series of high quality 300mm GaN-on-Si HEMT epi wafers for 200V, 650V and 1200V power applications with excellent thickness uniformity and lower wafer bow within 50μm;

Recent Progress with Multi-channel epi-wafers



Highlights:

- Multi-channel AlGaN/GaN hetero-structure builds several conductive channels into the component so as to distribute the flow of current - much like new lanes that are added to a highway to allow traffic to flow more smoothly and prevent traffic jams.
- Enkris is able to integrate multi-channel heterostructure on Si/SiC/Sapphire, etc.

Reference:

[1] Multi-channel AlGaN/GaN hetero-structure BV>10kV

IEEE Electron Device Letters, vol. 42, No. 6, June 2021
[2] Nanowire transistor on multi-channel heterostructure

Nature Electronics volume 4, pages 284–290 (2021)



